

C1206C102M2TACTU

Aliases (C1206C102M2TAC7800)

SMD Comm X8G HT150C, Ceramic, 1,000 pF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

1,000 pF

1 MHz 1.0Vrms

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.1mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

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Т	1.1mm +/-0.10mm	
S	1.5mm MIN	
В	0.5mm +/-0.25mm	
Packaging Specifications		

W	1.6mm +/-0.2mm	Tolerance	20%
Т	1.1mm +/-0.10mm	Voltage DC	200 VDC
S	1.5mm MIN	Dielectric Withstanding Voltage	500 VDC
В	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity	2500	Dissipation Factor	0.1% 1 MHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Specifications

Measurement Condition

Capacitance

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Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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